IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s):	David Jon Hiner et al.		
Assignee:	Amkor Technology, Inc.		
Title:	METHOD OF MANUFACTURING A SEMICONDUCTOR PACKAGE		
Serial No.:	10/806,640	Filed:	March 23, 2004
Examiner:	Carl J. Arbes	Group Art Unit:	3729
Docket No.:	G0092-6P		

Monterey, CA
February 16, 2007

Mail Stop Issue Fee
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

INFORMATION DISCLOSURE STATEMENT UNDER §1.97

Sir:

Pursuant to 37 C.F.R. §§ 1.56, 1.97 and 1.98, Applicant(s) wish to call the following documents to the attention of the Examiner. At a minimum, this Information Disclosure Statement should be placed in the file pursuant to 37 C.F.R. § 1.97(i).

U.S. PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	NAME
1)	4,806,188	02/21/89	Rellick
2)	7,030,469	04/18/06	Mahadevan et al.

OTHER DOCUMENTS

1)	Hiner et al., U.S. Patent Application Serial No. 10/992,371, filed on November 18, 2004, entitled "PRINTED WIRING MOTHERBOARD HAVING BONDED INTERCONNECT REDISTRIBUTION MESA"
2)	Scanlan et al., U.S. Patent Application Serial No. 11/293,999, filed on December 5, 2005, entitled "SEMICONDUCTOR PACKAGE INCLUDING A TOP-SURFACE METAL LAYER FOR IMPLEMENTING CIRCUIT FEATURES"

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3)	Huemoeller et al., U.S. Patent Application Serial No. 11/497,617, filed on August 1, 2006, entitled "BUILDUP DIELECTRIC AND METALLIZATION PROCESS AND SEMICONDUCTOR PACKAGE"
4)	Hiner et al., U.S. Patent Application Serial No. 11/595,411, filed November 9, 2006, entitled "SEMICONDUCTOR PACKAGE INCLUDING TOP-SURFACE TERMINALS FOR MOUNTING ANOTHER SEMICONDUCTOR PACKAGE"

A PTO form 1449 listing these documents is enclosed.

Citation of the above documents shall not be construed as:

1. an admission that the documents are necessarily prior art with respect to the instant invention;

2. a representation that a search has been made, other than as described above; or

3. an admission that the information cited herein is, or is considered to be, material to patentability as defined in § 1.56(b).

The Commissioner is hereby authorized to charge any fees required for consideration of this Information Disclosure Statement, and to credit any overpayment of fees to Deposit Account No. 50-0553.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on February 16, 2007.

Attorney for Applicant(s)

February 16, 2007
Date of Signature

Respectfully submitted,

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Form PTO-1449	Atty Docket No.	Serial No.
INFORMATION DISCLOSURE CITATION IN AN APPLICATION	G0092-6P	10/806,640
	Applicant(s) David Jon Hiner et al.	
(Use several sheets if necessary)	Filing Date March 23, 2004	Group 3729

U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	AA	4,806,188	02/21/89	Rellick	156	89	
	AB	7,030,469	04/18/06	Mahadevan et al.	257	659	
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						

FOREIGN PATENT DOCUMENTS

							Translation	
		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	YES	NO
	AK							
	AL							
	AN							
	AM							

OTHER DOCUMENTS (*Including Author, Title, Date, Pertinent Pages, Etc.*)

	AO	Hiner et al., U.S. Patent Application Serial No. 10/992,371, filed on November 18, 2004, entitled "PRINTED WIRING MOTHERBOARD HAVING BONDED INTERCONNECT REDISTRIBUTION MESA"
	AP	Scanlan et al., U.S. Patent Application Serial No. 11/293,999, filed on December 5, 2005, entitled "SEMICONDUCTOR PACKAGE INCLUDING A TOP-SURFACE METAL LAYER FOR IMPLEMENTING CIRCUIT FEATURES"
	AQ	Huemoeller et al., U.S. Patent Application Serial No. 11/497,617, filed on August 1, 2006, entitled "BUILDUP DIELECTRIC AND METALLIZATION PROCESS AND SEMICONDUCTOR PACKAGE"
	AR	Hiner et al., U.S. Patent Application Serial No. 11/595,411, filed November 9, 2006, entitled "SEMICONDUCTOR PACKAGE INCLUDING TOP-SURFACE TERMINALS FOR MOUNTING ANOTHER SEMICONDUCTOR PACKAGE"

Examiner	Date Considered

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant(s).